

Filed

: Herewith

introducing includes intermittently closing an inlet of the auxiliary chamber after introduction of the at least one of a first etchant and a first etch catalyst. The outlet of the auxiliary chamber is opened to discharge the at least one of a first etchant and a first etch catalyst into the etching chamber so that the inlet is closed when the outlet is opened. At least one of a second etchant and a second etch catalyst originating from a second source is introduced into the etching chamber via a second path. The substrate is etched and the etching chamber is flushed following the etching. The substrate is then removed from the etching chamber.--

On page 4, between lines 11 and 12, please insert--Brief Description of the Drawings--;

On page 4, between lines 16 and 17, please insert --Detailed Description of the
Invention--;

On page 8, line 1, please replace "Claims" with--WHAT IS CLAIMED --.

IN THE CLAIMS:

Please cancel Claims 1-10 without prejudice.

Please add new claims as follows:

11. A method for etching a substrate, comprising:

placing a substrate in an etching chamber;

introducing at least one of a first etchant and a first etch catalyst originating from a first source into said etching chamber via an auxiliary chamber positioned within a first path, said introducing comprising intermittently closing an inlet of the auxiliary chamber after introduction of said at least one of a first etchant and a first etch catalyst followed by opening an outlet of the auxiliary chamber to discharge said at least one of a first etchant and first etch catalyst into said etching chamber, such that the inlet is closed when the outlet is opened;

introducing at least one of a second etchant and a second etch catalyst originating from a second source via a second path;

etching said substrate;

flushing said etching chamber; and